–	6	((cvp cmp polish$3 etch$3) and (dummy near (holder stage platform platen wafer))) and (((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.))	USPAT; US-PGPUB	2003/08/10 20:38
–	23	((cvp cmp polish$3 etch$3) and (dummy near (holder stage platform platen wafer))) and (lens same (housing chamber))	USPAT; US-PGPUB	2003/08/10 20:42
–	23	(((cvp cmp polish$3 etch$3) and (dummy near (holder stage platform platen wafer))) and (lens same (housing chamber))) not (((cvp cmp polish$3 etch$3) and (dummy near (holder stage platform platen wafer))) and (((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.)))	USPAT; US-PGPUB	2003/08/10 20:42
–	5807	((cvp cmp polish$ etch$) and (lens same (housing chamber)))	USPAT; US-PGPUB	2003/08/10 20:51
–	672	(((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck))	USPAT; US-PGPUB	2003/08/10 20:52
–	1	(((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.)) and ((((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck)))	USPAT; US-PGPUB	2003/08/10 20:53
–	242	((((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)	USPAT; US-PGPUB	2003/08/10 20:53
–	160	(((((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract$ exhaust)	USPAT; US-PGPUB	2003/08/10 20:53
–	56	((((((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract$ exhaust)) and nozzle	USPAT; US-PGPUB	2003/08/10 20:55
–	51	(((((((cvp cmp polish$ etch$) and (lens same (housing chamber)))) and ((first second$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract$ exhaust)) and nozzle) and valve	USPAT; US-PGPUB	2003/08/10 20:55
–	46	5669979.URPN.	USPAT	2004/05/12 16:10
–	76	5571366.URPN.	USPAT	2004/05/12 16:14
–	222	(wafer same (dummy reference gold$2)) and (lens and nozzle)	USPAT	2004/05/12 16:17
–	16	((wafer same (dummy reference gold$2)) and (lens and nozzle)) and ((other another differ$ two second$3) near nozzle)	USPAT	2004/05/12 16:20
–	16	((wafer same (dummy reference gold$2)) and (lens and nozzle)) and ((other another differ$ two second$3 dual) near nozzle)	USPAT	2004/05/12 16:36
–	564	wafer and ((other another differ$ two second$3 dual) near nozzle)	USPAT	2004/05/12 16:24

—	171	(wafer and ((other another differ$ two second$3 dual) near nozzle)) and exhaust$	USPAT	2004/05/12 16:21
—	14	((wafer and ((other another differ$ two second$3 dual) near nozzle)) and exhaust$) and lens	USPAT	2004/05/12 16:21
—	87	(wafer and ((other another differ$ two second$3 dual) near nozzle)) and cmp	USPAT	2004/05/12 16:31
—	60	("3649509" | "3727620" | "3770598" | "4027686" | "4092176" | "4110176" | "4113492" | "4315059" | "4326940" | "4336114" | "4376685" | "4405416" | "4428815" | "4435266" | "4489740" | "4510176" | "4518678" | "4519846" | "4529353" | "4693805" | "4732785" | "4789445" | "4981715" | "5039381" | "5055425" | "5092975" | "5100502" | "5155336" | "5162260" | "5222310" | "5224504" | "5230743" | "5252807" | "5256274" | "5259407" | "5290361" | "5316974" | "5328589" | "5344491" | "5349978" | "5368711" | "5377708" | "5382885" | "5415890" | "5429733" | "5447615" | "5516412" | "5608943" | "5625170" | "5651865" | "5705223" | "5718813" | "5723028" | "5811951" | "5975834" | "6071388" | "6093291" | "6136163" | "6254760" | "6258220").PN.	USPAT	2004/05/12 16:25
—	1903	array near nozzle	USPAT	2004/05/12 16:31
—	255	(array near nozzle) and wafer	USPAT	2004/05/12 16:31
—	97	(array near nozzle) and (wafer same (clean$ polish$))	USPAT	2004/05/12 16:31
—	353	lens and ((other another differ$ two second$3 dual) near nozzle)	USPAT	2004/05/12 16:36
—	169	(lens and ((other another differ$ two second$3 dual) near nozzle)) and (wafer semiconduct$ substrate)	USPAT	2004/05/12 16:37
—	11	((wafer substrate semiconduct$) near clean$) and (separate near nozzle)	USPAT	2004/05/12 16:43
—	72	platen near chuck	USPAT	2004/05/12 17:02
—	40	(platen near chuck) same wafer	USPAT	2004/05/12 17:06
—	17	(laser near clean$) and ((reference standard$ dummy gold$2) near (wafer semiconduct$ substrate))	USPAT	2004/05/12 17:17
—	150	(laser same clean$) and ((reference standard$ dummy gold$2) near (wafer semiconduct$ substrate))	USPAT	2004/05/12 17:17
—	133	((laser same clean$) and ((reference standard$ dummy gold$2) near (wafer semiconduct$ substrate))) not ((laser near clean$) and ((reference standard$ dummy gold$2) near (wafer semiconduct$ substrate)))	USPAT	2004/05/12 17:22
—	12	4512659.URPN.	USPAT	2004/05/12 17:20
—	46	(calibrat$ near wafer) same (support holder platen chuck stage)	USPAT	2004/05/12 17:22
—	183	(wafer same (clean$ process$3)) and ((exhaust vacuum evacuat$) same venturi)	USPAT; US-PGPUB	2004/05/12 17:42
—	46	((wafer same (clean$ process$3)) and ((exhaust vacuum evacuat$) same venturi)) and cmp	USPAT; US-PGPUB	2004/05/12 17:42
—	4	((wafer same (clean$ process$3)) and ((exhaust vacuum evacuat$) same venturi)) and (laser same clean$)	USPAT; US-PGPUB	2004/05/12 17:42

L Number	Hits	Search Text	DB	Time stamp
127	219	(359/509).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16
128	461	(356/36).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16
129	454	(156/345.12,345.13,345.15).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16

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